

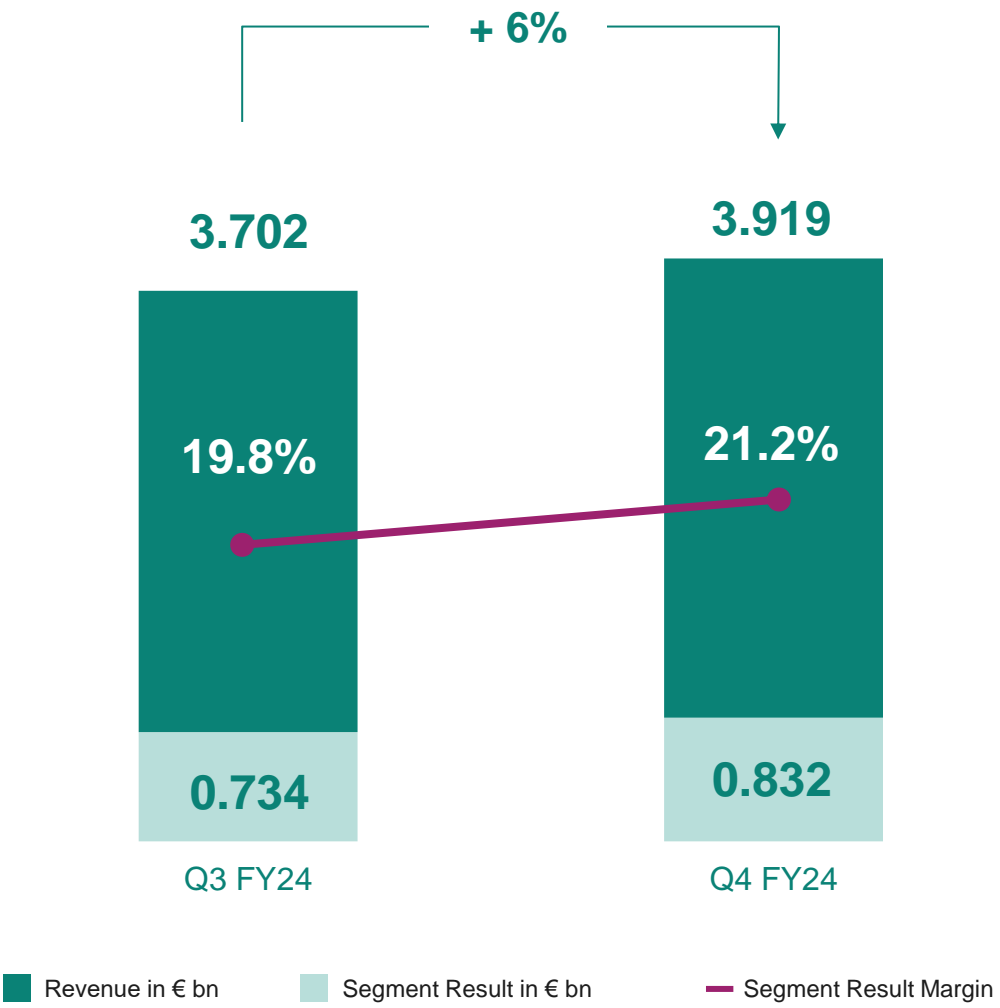


# Annual Press Conference 2024

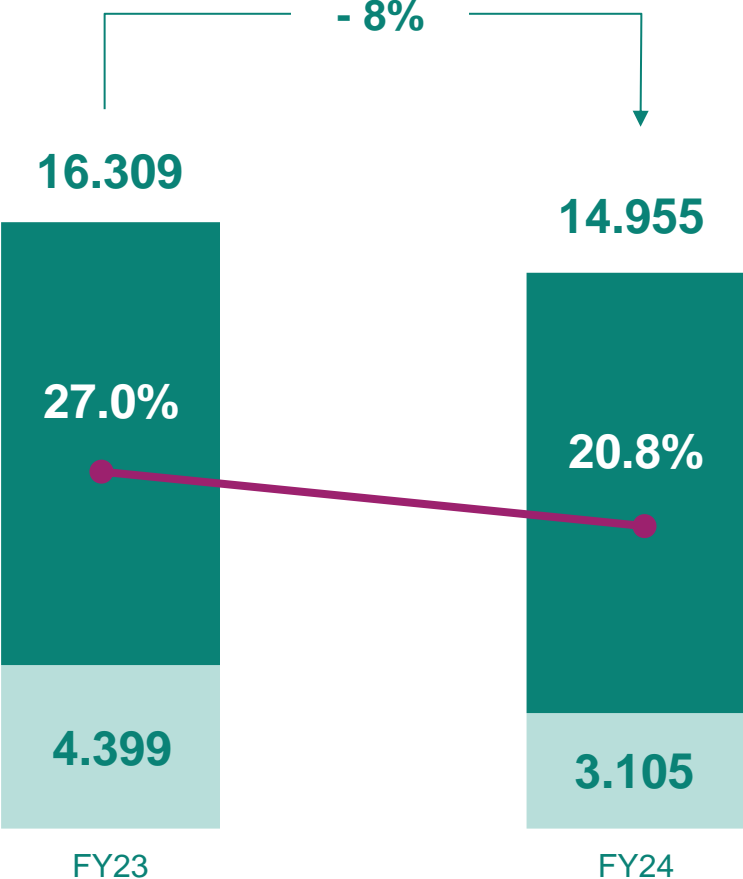
Jochen Hanebeck, Chief Executive Officer  
Infineon Technologies AG | Neubiberg, 12 November 2024



# Infineon increases revenue and earnings in the fourth quarter



# 2024 fiscal year concluded in line with expectations



Decline in revenue after record 2023 fiscal year

Robust profitability

Numbers are in line with the long-term financial targets through the semiconductor cycle

■ Revenue in € bn   ■ Segment Result in € bn   — Segment Result Margin

# Thank you!

To around 58,000 employees  
worldwide for their contribution in the  
2024 fiscal year



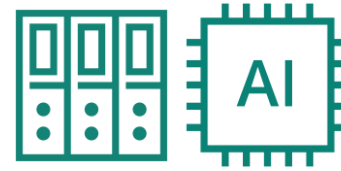
# Proposal to the Annual General Meeting: Stable dividend of 35 eurocents per share



# Infineon is paving the way for the green and digital transformation



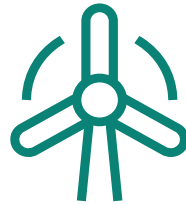
**Software-defined vehicles**



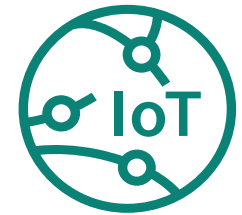
**Data centers, especially for artificial intelligence (AI)**



**Electromobility**



**Renewable energies**



**Internet of Things (IoT)**

**Unabated growth opportunities for Infineon**



**Come visit us.  
We look forward to seeing  
you!**

***Hall C3, Booth 502***

# Stellantis and Infineon deepen collaboration

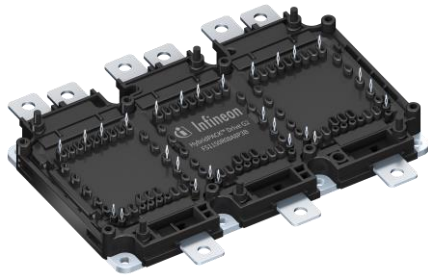


Innovation in power conversion and distribution for next generation vehicle architectures

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Major supply and capacity agreements have been signed

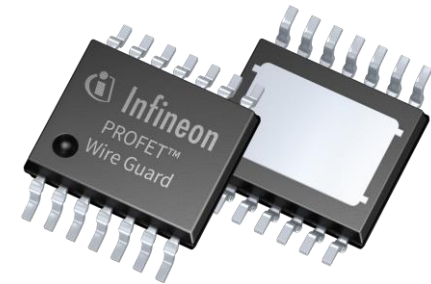
CoolSiC™ power modules



AURIX™ microcontrollers



PROFET™ smart power switches





# Power for the energy transition: Our innovative power semiconductor module for high-current applications

**Renewable energies**

**Electrification**

**Energy efficiency**



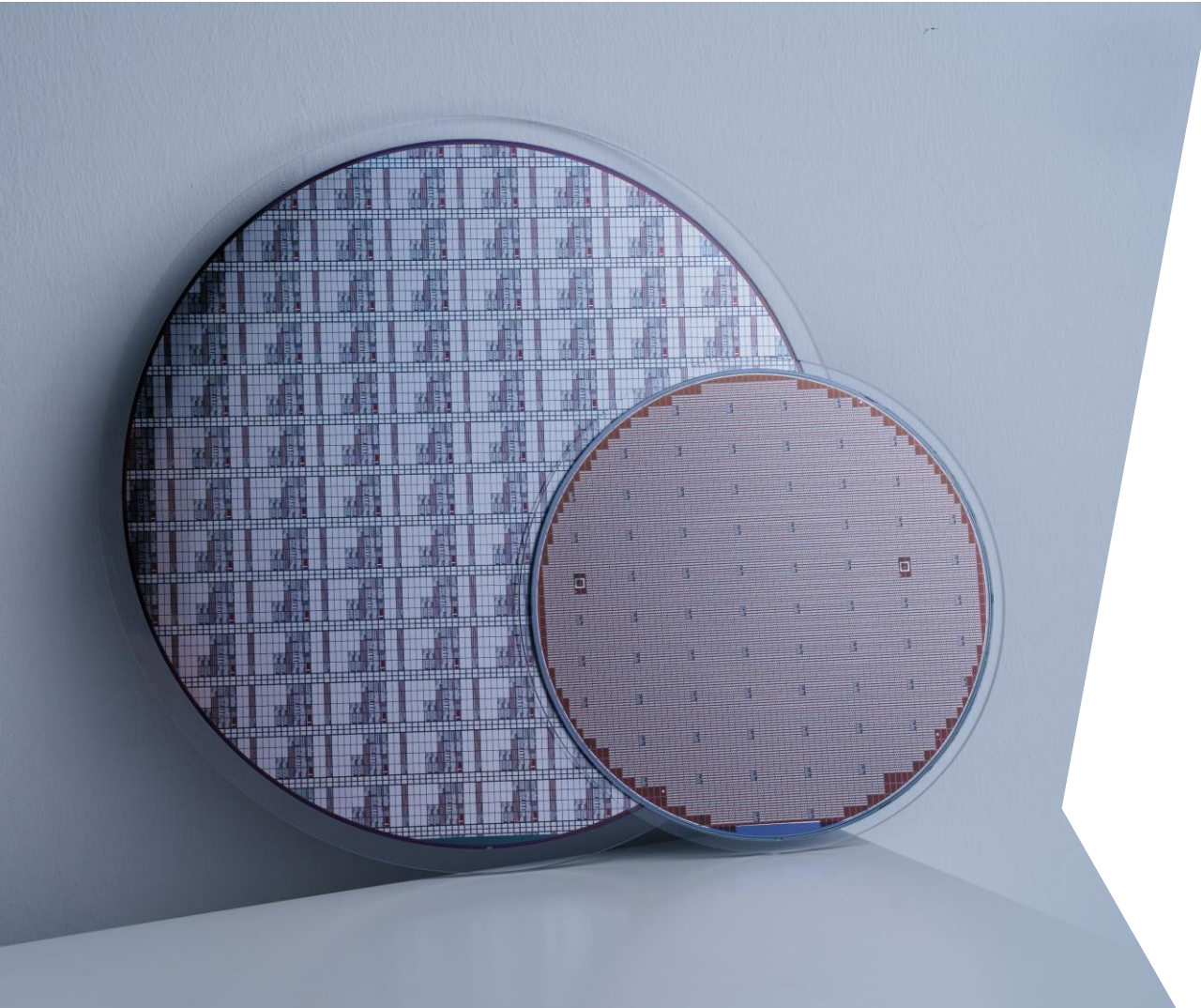
✓ 90 percent fewer switching losses\*

✓ 10 times more power per module \*

✓ 10 times longer service life\*

\*Compared to state of the art 3.3kV silicon-based power semiconductor module

# We will shape the market for GaN-based power semiconductors



World's **first GaN wafer technology** for power electronics on **300 mm wafers**

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Chip production on 300 mm wafers:  
**2.3 times more chips per wafer**

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Existing 300 mm silicon manufacturing equipment can also be used for 300 mm GaN technology

# Infineon unveils the world's thinnest silicon power wafer



Handling and processing of  
**ultra-thin power semiconductor wafers**

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Enables **power loss reductions** of more than  
**15 percent** in power systems

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Can be used in numerous application areas

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Strengthens Infineon's **Powering AI** roadmap

# Leading provider of power systems: We set the pace in all three power semiconductor technologies



Leader in power systems –  
mastering all three technologies

Si

SiC



GaN



Outstanding **manufacturing expertise**

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Most comprehensive  
**technology and product portfolio**

---

Wide **range of applications**

# Outlook for the 2025 fiscal year: Muted expectations in a weak market environment



	Outlook <b>Q1 FY 2025<sup>1</sup></b>	Outlook <b>FY 2025<sup>1</sup></b>
<b>Revenue</b>	~ € 3.2 bn	Slight decline year-on-year
<b>Segment Result Margin</b>	In the mid-teens percentage range	In the mid-to-high teens percentage range
<b>Adjusted/ Reported Free Cash Flow</b>		~ € 1.7 bn / ~ € 0.9 bn
<b>Investments</b>		~ € 2.5 bn

<sup>1</sup> Based on an assumed exchange rate of US\$1.10 to the euro

# Summary

The cyclical recovery is sluggish. We expect a slight decline in revenue in the 2025 fiscal year.

We are concentrating on the areas that we can control. In this way we are strengthening our profitability and competitiveness.

We are consolidating our position as an innovation leader and are optimally positioning Infineon for the future.



